

AMENDMENTS IN THE CLAIMS:

1. (Currently Amended) A semiconductor device package structure comprising:
~~a semiconductor chip mounted interposer configured by mounting a~~
semiconductor chip to an interposer in which inside terminals to which terminals of a
semiconductor chip to be mounted are connected, outside terminals to which terminals
other than the terminals of the semiconductor chip are connected, and conductive wiring
that makes an electrical connection between the outside terminals and the inside
terminals are formed, and

a substrate-like or frame-like base material on which a plurality of semiconductor
chips are mounted, wherein

a semiconductor chip mounted interposer configured by mounting a
semiconductor bare chip on an interposer in which inside terminals to which terminals of
the mounted semiconductor bare chip are connected, outside terminals to which
terminals other than the terminals of the semiconductor bare chip are connected, testing
terminals to which testing electrodes of a testing apparatus are connected, and
conductive wiring that makes an electrical connection between the inside terminals, the
outside terminals and the testing terminals, are formed, and detaching the testing
terminals after predetermined reliability testing or operation testing, wherein

the semiconductor chip mounted interposer is mounted along with another
semiconductor chip to the base material, and the semiconductor chip mounted
interposer and the other semiconductor chip are resin sealed along with the base
material.

2-6. (Cancelled)

7. (Currently Amended) ~~The semiconductor device package structure according to~~
~~claim 1, wherein the interposer, in a state before being mounted to the base material, is~~
~~provided with terminals for connecting to a testing apparatus in order to perform~~
~~predetermined reliability testing or operation testing, and the semiconductor chip~~

~~mounted interposer, in a state before being mounted to the base material, has been subjected to the predetermined reliability testing or operation testing using the terminals.~~

A semiconductor chip mounted interposer, configured by mounting a semiconductor bare chip on an interposer in which inside terminals to which terminals of the mounted semiconductor bare chip are connected, outside terminals to which terminals other than the terminals of the semiconductor bare chip are connected, testing terminals to which testing electrodes of a testing apparatus are connected, and conductive wiring that makes an electrical connection between the inside terminals, the outside terminals and the testing terminals, are formed, and
detaching the testing terminals after predetermined reliability testing or operation testing.

8. (Currently Amended) ~~A semiconductor device packaging method comprising configuring a semiconductor chip mounted interposer by mounting a semiconductor chip to an interposer in which inside terminals to which terminals of a semiconductor chip to be mounted are connected, outside terminals to which terminals other than the terminals of the semiconductor chip are connected, and conductive wiring that makes an electrical connection between the outside terminals and the inside terminals, are formed; mounting the semiconductor chip mounted interposer to a substrate-like or frame-like base material; and resin-sealing the semiconductor chip mounted interposer together along with the base material.~~

A fabrication method for a semiconductor chip mounted interposer, comprising: producing an interposer in which inside terminals to which terminals of the mounted semiconductor bare chip are connected, outside terminals to which terminals other than the terminals of the semiconductor bare chip are connected, testing terminals to which testing electrodes of a testing apparatus are connected, and conductive wiring that makes an electrical connection between the inside terminals, the outside terminals and the testing terminals, are formed,
mounting the semiconductor bare chip on the interposer, and connecting terminals of the semiconductor bare chip to the inside terminals,

performing predetermined reliability testing or operation testing by connecting a testing apparatus to the testing terminals, and

producing a semiconductor chip mounted interposer by detaching the testing terminals after the predetermined reliability testing or operation testing.

9. (Cancelled)

10. (New) The fabrication method for a semiconductor chip mounted interposer according to claim 8, wherein the production of the interposer is performed by joining a plurality of interposers in a single body in the form of a matrix, and

the operation testing is performed by consecutively or simultaneously performing the initial reliability testing or operation testing for the plurality of interposers joined in a single body.

11. (New) A bare chip mounted interposer, in which:

inside terminals to which terminals of a mounted semiconductor bare chip are connected,

outside terminals to which terminals other than the terminals of the semiconductor bare chip are connected,

testing terminals for connecting testing electrodes of a testing apparatus, formed on the outer side of the inside terminals and the outside terminals, with a larger pitch than the inside terminals and the outside terminals, and

conductive wiring that makes an electrical connection between the outside terminals, the inside terminals, and the testing terminals, are formed.

12. (New) An interposer sheet configured by joining a plurality of the interposers according to claim 11 in a single body in the form of a matrix.